

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10585461
<b>Filing Date:</b>	
<b>Title of Invention:</b>	Circuit connection material, film-shaped circuit connection material using the same, circuit member connection structure, and manufacturing method thereof
<b>First Named Inventor/Applicant Name:</b>	Jun Taketatsu
<b>Filer:</b>	William Ivan Solomon/Ricardo Perez
<b>Attorney Docket Number:</b>	1303.46354X00

Filed as Large Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
Oath/decl > 30 months from priority date	1617	1	130	130
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130